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FCP20N60 / FCPF20N60 N-Channel SuperFET[®] MOSFET 600 V, 20 A, 190 mΩ

Features

- 650V @ T_{.1} = 150°C
- Typ. R_{DS(on)} = 150 mΩ
- Ultra Low Gate Charge (Typ. Q_q = 75 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 165 pF)
- 100% Avalanche Tested

Applications

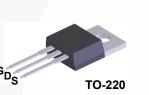
- Solar Inverter
- AC-DC Power Supply

August 2014

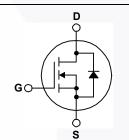
FCP20N60 / FCPF20N60 — N-Channel SuperFET[®] MOSFET

Description

SuperFET[®] MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







Absolute Maximum Ratings

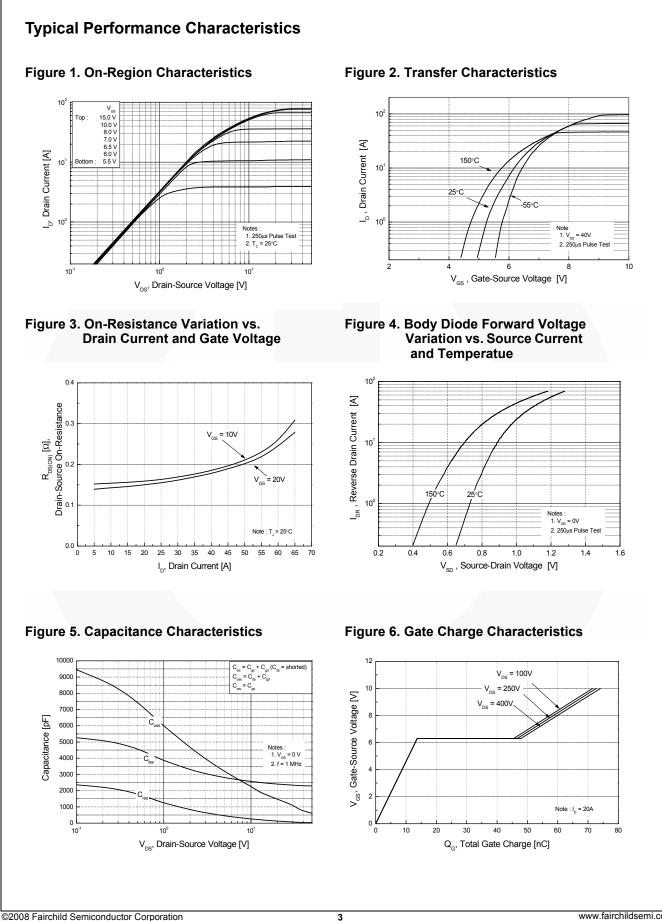
Symbol		Parameter		FCP20N60	FCPF20N60	Unit
V _{DSS}	Drain-Source Voltage			6	V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		20 12.5	20* 12.5*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	60	60*	А
V _{GSS}	Gate-Source Voltage			± 30		V
E _{AS}	Single Pulsed Avala	anche Energy	(Note 2)	690		mJ
I _{AR}	Avalanche Current		(Note 1)	20		А
E _{AR}	Repetitive Avalanch	ve Avalanche Energy (Note 1) 20.8		0.8	mJ	
dv/dt	Peak Diode Recove	ery dv/dt	(Note 3)	4.5		V/ns
P _D	Power Dissipation	(T _C = 25°C) - Derate Above 25°C		208 1.67	39 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C	
Τ _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300		°C

*Drain current limited by maximum junction temperature.

Thermal Characteristics

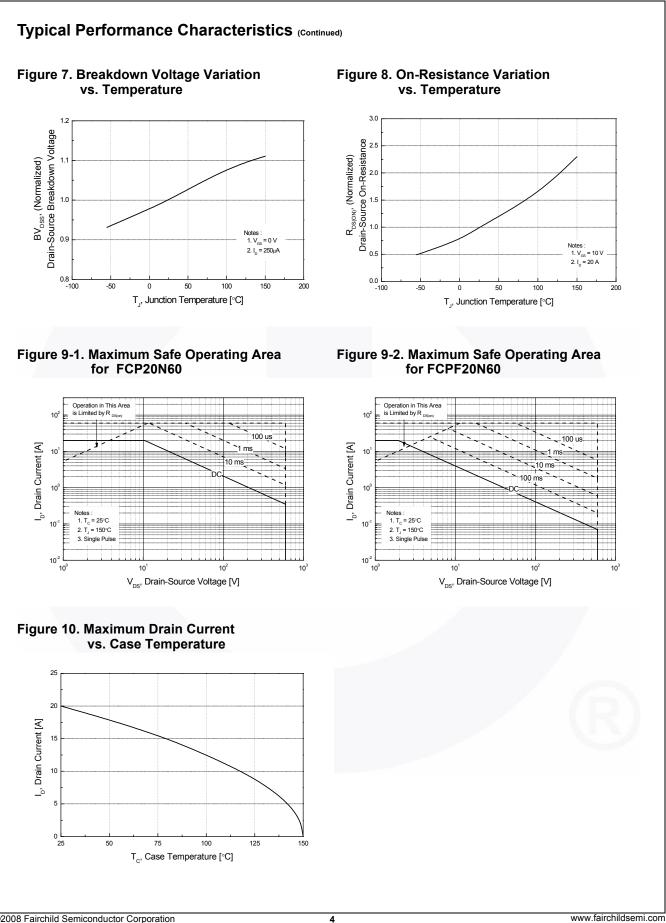
Symbol	Parameter	FCP20N60	FCPF20N60	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction-to-Case	0.6	3.2	°C/W
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

nber	Top Mark	Package	Packing Method	Reel Size	Тар	e Width	Qua	ntity
160	FCP20N60	TO-220	Tube	N/A		N/A	50 units	
		TO-220F	20F Tube N/A		N/A		50 units	
I Char	acteristics T _c = 2	25ºC unless	otherwise noted.					
	Parameter		Test Conditions			Тур.	Max.	Unit
teristic	S							
Drain to Source Breakdown Voltage		ade	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 25^{o}C$			-	-	V
		0	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}C$			650	-	V
Breakdown Voltage Temperature		9	I_D = 250 μ A, Referenced to 25°C			0.6	-	V/°C
Drain-Source Avalanche Breakdown Voltage		lown	V _{GS} = 0 V, I _D = 20 A		-	700	-	v
Zero Ga	Zero Gate Voltage Drain Current		V _{DS} = 600 V, V _{GS} = 0 V		-	-	1	μA
		•			-	-	10	
Gate to	Body Leakage Current		$V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$	/	-	-	±100	nA
teristics	S							
Gate Th	ate Threshold Voltage		V _{GS} = V _{DS} , I _D = 250 μA			-	5.0	V
Static D	c Drain to Source On Resistance		V _{GS} = 10 V, I _D = 10 A		-	0.15	0.19	Ω
Forward	Forward Transconductance		V _{DS} = 40 V, I _D = 10 A			17	-	S
haracte	eristics							
	Capacitance ut Capacitance		V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		-	2370	3080	pF
Output 0					-	1280	1665	pF
Reverse					-	95	-	pF
Output 0	Capacitance		V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz		-	65	85	pF
Effective	e Output Capacitance		$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$		-	165	-	pF
Total Ga	te Charge at 10V		V _{DS} = 480 V. I _D = 20 A.		-	75	98	nC
Gate to	to Source Gate Charge		V _{GS} = 10 V		-	13.5	18	nC
Gate to	Drain "Miller" Charge		(Note 4)			36	-	nC
Charact	teristics							
						62	135	ns
Turn-On			V _{DD} = 300 V, I _D = 20 A,		-	140	290	ns
Turn-Off Delay Time			$V_{GS} = 10 \text{ V}, \text{ R}_{G} = 25 \Omega$ (Note 4)			230	470	ns
						65	140	ns
	la Charactoristics					I	/	
		ource Diode	Forward Current		-	_	20	Α
_					-	-		A
					_	-		V
	•				-	530	-	ns
	Recovery Charge		$dI_{\rm F}/dt = 100 \text{ A}/\mu \text{s}$			10.5	-	μC
	teristics Drain to Breakdo Coefficie Drain-So Voltage Zero Ga Gate to Eristics Gate to Static D Forwarce Input Ca Output C Reverse Output C Effective Total Ga Gate to Gate to Gate to Gate to Charact Turn-On Turn-Off Turn-Off Turn-Off Ce Dioc	Parameter teristics Drain to Source Breakdown Volt Breakdown Voltage Temperature Coefficient Drain-Source Avalanche Breakdown Voltage Zero Gate Voltage Drain Curren Gate to Body Leakage Current teristics Gate Threshold Voltage Static Drain to Source On Resis Forward Transconductance tharacteristics Input Capacitance Output Capacitance Output Capacitance Output Capacitance Effective Output Capacitance Gate to Source Gate Charge Gate to Drain "Miller" Charge Characteristics Turn-On Delay Time Turn-Off Delay Time Turn-Off Fall Time ce Diode Characteristics Maximum Continuous Drain to Source	Parameter teristics Drain to Source Breakdown Voltage Breakdown Voltage Temperature Coefficient Drain-Source Avalanche Breakdown Voltage Zero Gate Voltage Drain Current Gate to Body Leakage Current teristics Gate Threshold Voltage Static Drain to Source On Resistance Forward Transconductance Protecteristics Input Capacitance Output Capacitance Output Capacitance Output Capacitance Output Capacitance Gate to Drain "Miller" Charge Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Ce Diode Characteristics Maximum Continuous Drain to Source Diode Maximum Pulsed Drain to Source Diode Forward Voltage	teristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, ReferenceDrain-Source Avalanche Breakdown Voltage $V_{GS} = 0 \ V$, $I_D = 20 \ A$ Zero Gate Voltage Drain Current $V_{DS} = 600 \ V$, $V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = 480 \ V$, $T_C = 125^\circ$ Gate Threshold Voltage $V_{GS} = \pm 30 \ V$, $V_{DS} = 0 \ V$ Static Drain to Source On Resistance $V_{GS} = 10 \ V$, $I_D = 10 \ A$ Forward Transconductance $V_{DS} = 400 \ V$, $I_D = 10 \ A$ PharacteristicsInput CapacitanceInput Capacitance $V_{DS} = 25 \ V$, $V_{GS} = 0 \ V_{CS} = 10 \ V$, $I_D = 10 \ A$ CharacteristicsVoing = 25 \ V, $V_{GS} = 0 \ V_{CS} = 480 \ V$, $I_D = 10 \ A$ PharacteristicsVoing = 25 \ V, $V_{GS} = 0 \ V_{CS} = 10 \ V_{CS} = 0 \ V_{CS} = 10 \ V$ Input Capacitance $V_{DS} = 480 \ V, I_D = 20 \ A$ Output Capacitance $V_{DS} = 480 \ V, I_D = 20 \ A$ Gate to Source Gate Charge $V_{CS} = 10 \ V$ Gate to Drain "Miller" ChargeCharacteristicsTurn-On Delay TimeTurn-Off Delay TimeTurn-Off Fall TimeCe Diode CharacteristicsMaximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentDrain to Source Diode Forward VoltageV _{GS} = 0 V, I _{SD} = 20 \ A </td <td>ParameterTest ConditionsteristicsDrain to Source Breakdown Voltage$\frac{I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 25^{\circ}C}{I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}C}$Breakdown Voltage Temperature Coefficient$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}C$Drain-Source Avalanche Breakdown Voltage$V_{GS} = 0 \ V, \ I_D = 20 \ A$Zero Gate Voltage Drain Current$V_{DS} = 600 \ V, \ V_{GS} = 0 \ V$Zero Gate Voltage Drain Current$V_{GS} = 480 \ V, \ T_C = 125^{\circ}C$Gate to Body Leakage Current$V_{GS} = 10 \ V, \ I_D = 10 \ A$Static Drain to Source On Resistance$V_{GS} = 10 \ V, \ I_D = 10 \ A$Forward Transconductance$V_{DS} = 480 \ V, \ I_D = 10 \ A$*tharacteristics$V_{DS} = 25 \ V, \ V_{GS} = 0 \ V, \ f = 1 \ MHz$Input Capacitance$V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{CS} = 0 \ V$Output Capacitance$V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{CS} = 0 \ V$Drain Capacitance$V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{GS} = 10 \ V, \ G_S = 10 \$</td> <td>$\begin{tabular}{ c c c c } \hline Parameter & Test Conditions & Min. \\ \hline teristics \\ \hline teristics \\ \hline teristics \\ \hline Drain to Source Breakdown Voltage & I_D = 250 \muA, V_{GS} = 0 V, T_J = 25^{\circ}C & 600 \\ I_D = 250 \muA, V_{GS} = 0 V, T_J = 150^{\circ}C & - \\ \hline Breakdown Voltage Temperature & I_D = 250 \muA, Referenced to 25^{\circ}C & - \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 0 V, I_D = 20 A & - \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 600 V, V_{GS} = 0 V & - \\ \hline V_{DS} = 480 V, T_C = 125^{\circ}C & - \\ \hline Gate to Body Leakage Current & V_{GS} = 430 V, V_{DS} = 0 V & - \\ \hline teristics & & & & & \\ \hline Gate Threshold Voltage & V_{GS} = V_{DS}, I_D = 250 \muA & 3.0 \\ \hline Static Drain to Source On Resistance & V_{GS} = 10 V, I_D = 10 A & - \\ \hline Forward Transconductance & V_{DS} = 40 V, I_D = 10 A & - \\ \hline Haracteristics & & & & & \\ \hline Input Capacitance & V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Output Capacitance & V_{DS} = 480 V, I_D = 20 A, & - \\ \hline Output Capacitance & V_{DS} = 480 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Output Capacitance & V_{DS} = 480 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Total Gate Charge at 10V & V_{DS} = 480 V, I_D = 20 A, & - \\ \hline Characteristics & & & & & & \\ \hline Turn-On Delay Time & & & & & & & & & \\ \hline Turn-On Rise Time & \\ \hline Turn-Off Belay Time & &$</td> <td>ParameterTest ConditionsMin.Typ.teristicsDrain to Source Breakdown Voltage$\frac{I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^\circ C}{I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^\circ C}$600-Breakdown Voltage Temperature Coefficient$I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^\circ C$-0.6Drain-Source Avalanche Breakdown Voltage$V_{GS} = 00 \ V, I_D = 20 \ A$-700Zero Gate Voltage Drain Current$V_{DS} = 600 \ V, V_{CS} = 0 \ V$Gate to Body Leakage Current$V_{GS} = 480 \ V, I_D = 102 \ A$Vos = 480 V, $V_{CS} = 10^{V}$Static Drain to Source On Resistance$V_{GS} = 10 \ V, I_D = 10 \ A$-0.15Forward Transconductance$V_{DS} = 480 \ V, I_D = 10 \ A$-17haracteristics2370-Output Capacitance$V_{DS} = 480 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$-655Total Gate Charge at 10V$V_{DS} = 480 \ V, V_{CS} = 0 \ V, f = 1 \ MHz$-656Total Gate Charge at 10V$V_{DS} = 480 \ V, I_D = 20 \ A, V_{CS} = 0 \ V, f = 1 \ MHz$-656Turn-On Delay TimeV_{DS} = 100 \ V, N_{CS} = 10 \ V, N_{CS} = 0 \ V, f = 1 \ MHz-622Turn-On Delay TimeV_{DS} = 300 \ V, I_D = 20 \ A, V_{CS} = 10 \ V, N_{CS} = 10 \ V, N_{CS</td> <td>$\begin{tabular}{ c c c c c } \hline Parameter Test Conditions Min. Typ. Max. \\ \hline teristics \\ \hline \begin{tabular}{ c c c c c } \hline Test Source Breakdown Voltage II_D = 250 \$\mu A, V_{GS} = 0 V, T_J = 25^{\circ}C & 600 & - &$</td>	ParameterTest ConditionsteristicsDrain to Source Breakdown Voltage $\frac{I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 25^{\circ}C}{I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}C}$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu A, \ V_{GS} = 0 \ V, \ T_J = 150^{\circ}C$ Drain-Source Avalanche Breakdown Voltage $V_{GS} = 0 \ V, \ I_D = 20 \ A$ Zero Gate Voltage Drain Current $V_{DS} = 600 \ V, \ V_{GS} = 0 \ V$ Zero Gate Voltage Drain Current $V_{GS} = 480 \ V, \ T_C = 125^{\circ}C$ Gate to Body Leakage Current $V_{GS} = 10 \ V, \ I_D = 10 \ A$ Static Drain to Source On Resistance $V_{GS} = 10 \ V, \ I_D = 10 \ A$ Forward Transconductance $V_{DS} = 480 \ V, \ I_D = 10 \ A$ *tharacteristics $V_{DS} = 25 \ V, \ V_{GS} = 0 \ V, \ f = 1 \ MHz$ Input Capacitance $V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{CS} = 0 \ V$ Output Capacitance $V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{CS} = 0 \ V$ Drain Capacitance $V_{DS} = 480 \ V, \ I_D = 20 \ A, \ V_{GS} = 10 \ V, \ G_S = 10 \$	$\begin{tabular}{ c c c c } \hline Parameter & Test Conditions & Min. \\ \hline teristics \\ \hline teristics \\ \hline teristics \\ \hline Drain to Source Breakdown Voltage & I_D = 250 \muA, V_{GS} = 0 V, T_J = 25^{\circ}C & 600 \\ I_D = 250 \muA, V_{GS} = 0 V, T_J = 150^{\circ}C & - \\ \hline Breakdown Voltage Temperature & I_D = 250 \muA, Referenced to 25^{\circ}C & - \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 0 V, I_D = 20 A & - \\ \hline Drain-Source Avalanche Breakdown & V_{GS} = 600 V, V_{GS} = 0 V & - \\ \hline V_{DS} = 480 V, T_C = 125^{\circ}C & - \\ \hline Gate to Body Leakage Current & V_{GS} = 430 V, V_{DS} = 0 V & - \\ \hline teristics & & & & & \\ \hline Gate Threshold Voltage & V_{GS} = V_{DS}, I_D = 250 \muA & 3.0 \\ \hline Static Drain to Source On Resistance & V_{GS} = 10 V, I_D = 10 A & - \\ \hline Forward Transconductance & V_{DS} = 40 V, I_D = 10 A & - \\ \hline Haracteristics & & & & & \\ \hline Input Capacitance & V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Output Capacitance & V_{DS} = 480 V, I_D = 20 A, & - \\ \hline Output Capacitance & V_{DS} = 480 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Output Capacitance & V_{DS} = 480 V, V_{GS} = 0 V, f = 1 MHz & - \\ \hline Total Gate Charge at 10V & V_{DS} = 480 V, I_D = 20 A, & - \\ \hline Characteristics & & & & & & \\ \hline Turn-On Delay Time & & & & & & & & & \\ \hline Turn-On Rise Time & & & & & & & & & & & & & \\ \hline Turn-Off Belay Time & & & & & & & & & & & & & & & & & & &$	ParameterTest ConditionsMin.Typ.teristicsDrain to Source Breakdown Voltage $\frac{I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 25^\circ C}{I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^\circ C}$ 600-Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu A, V_{GS} = 0 \ V, T_J = 150^\circ C$ -0.6Drain-Source Avalanche Breakdown Voltage $V_{GS} = 00 \ V, I_D = 20 \ A$ -700Zero Gate Voltage Drain Current $V_{DS} = 600 \ V, V_{CS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = 480 \ V, I_D = 102 \ A$ Vos = 480 V, $V_{CS} = 10^{V}$ Static Drain to Source On Resistance $V_{GS} = 10 \ V, I_D = 10 \ A$ -0.15Forward Transconductance $V_{DS} = 480 \ V, I_D = 10 \ A$ -17haracteristics2370-Output Capacitance $V_{DS} = 480 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ -655Total Gate Charge at 10V $V_{DS} = 480 \ V, V_{CS} = 0 \ V, f = 1 \ MHz$ -656Total Gate Charge at 10V $V_{DS} = 480 \ V, I_D = 20 \ A, V_{CS} = 0 \ V, f = 1 \ MHz$ -656Turn-On Delay TimeV_{DS} = 100 \ V, N_{CS} = 10 \ V, N_{CS} = 0 \ V, f = 1 \ MHz-622Turn-On Delay TimeV_{DS} = 300 \ V, I_D = 20 \ A, V_{CS} = 10 \ V, N_{CS} = 10 \ V, N_{CS	$\begin{tabular}{ c c c c c } \hline Parameter Test Conditions Min. Typ. Max. \\ \hline teristics \\ \hline \begin{tabular}{ c c c c c } \hline Test Source Breakdown Voltage II_D = 250 $\mu A, V_{GS} = 0 V, T_J = 25^{\circ}C & 600 & - & - & - & - & - & - & - & - & - &$

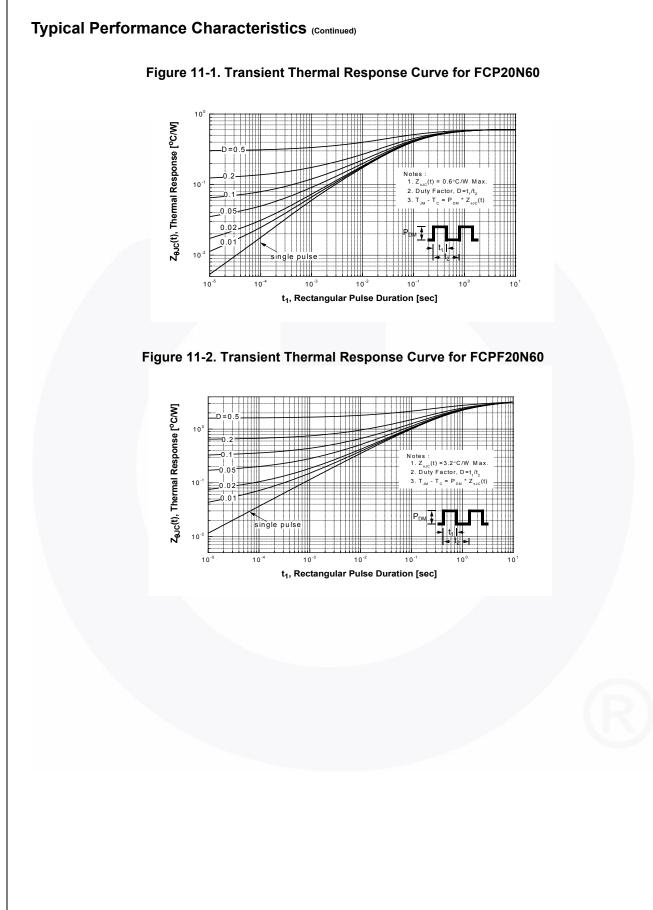


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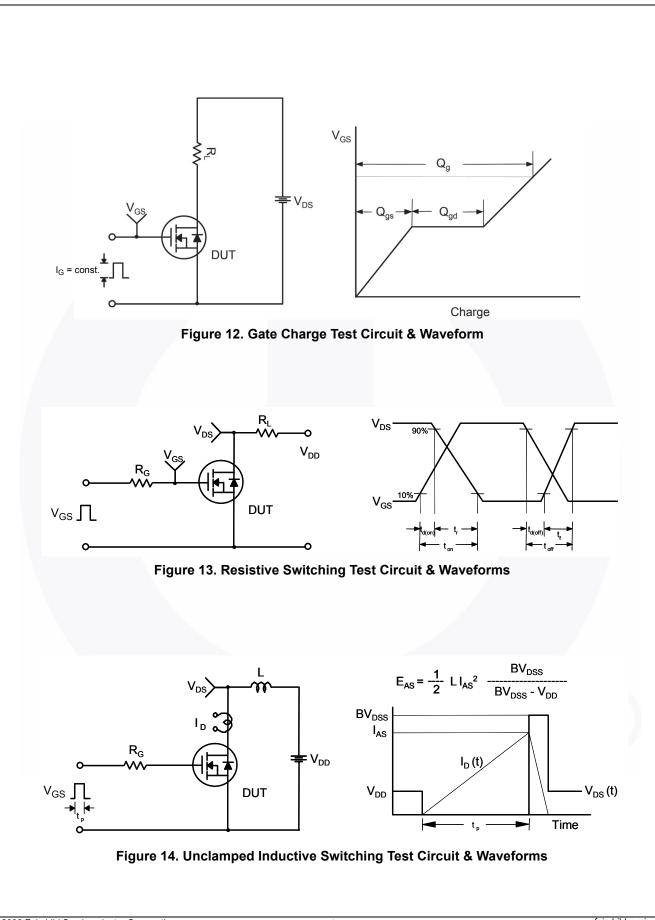
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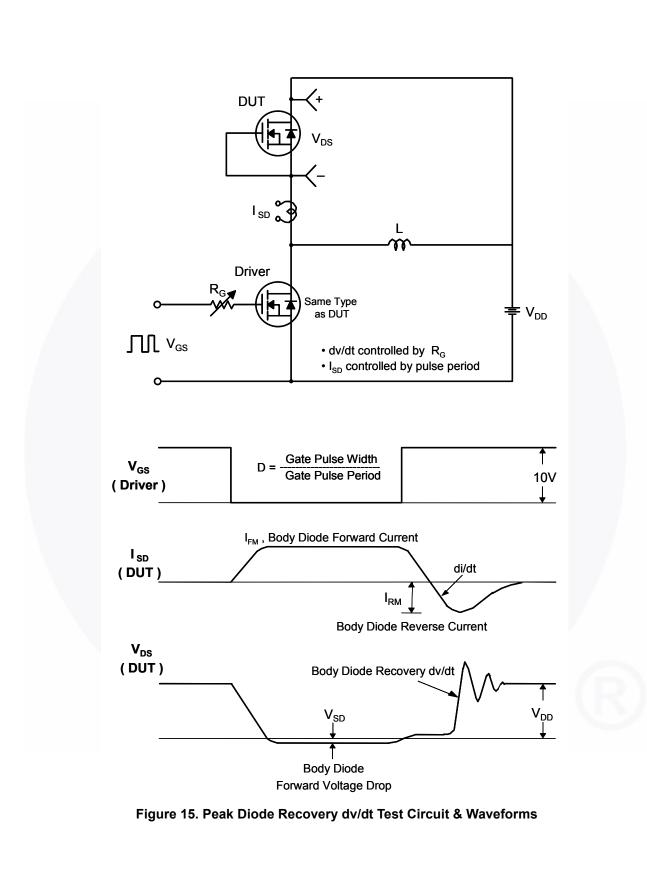
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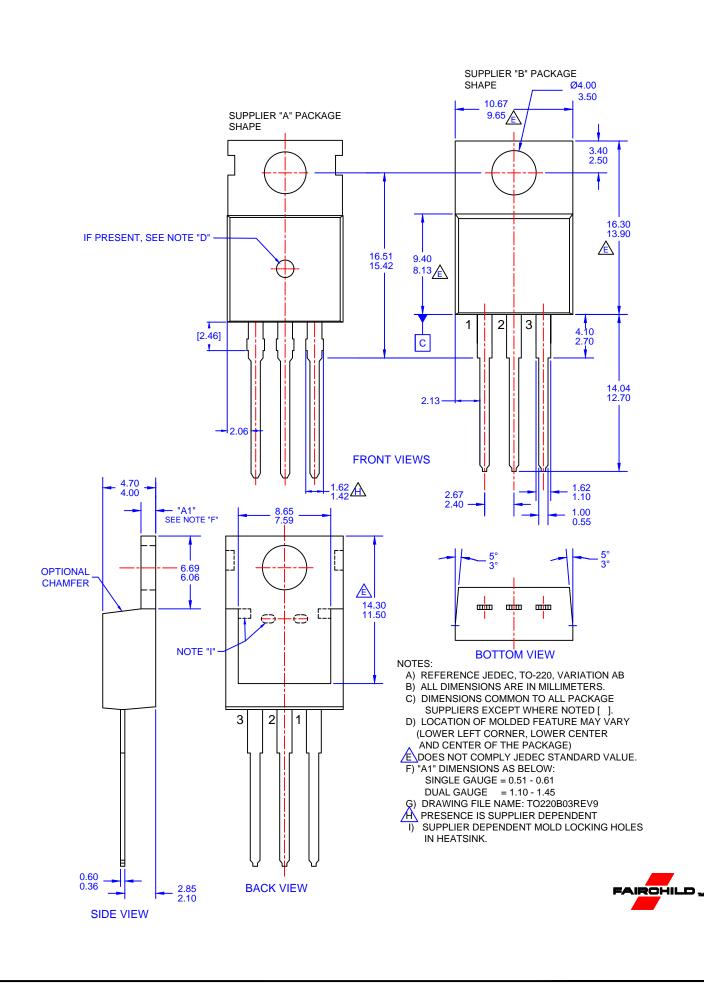
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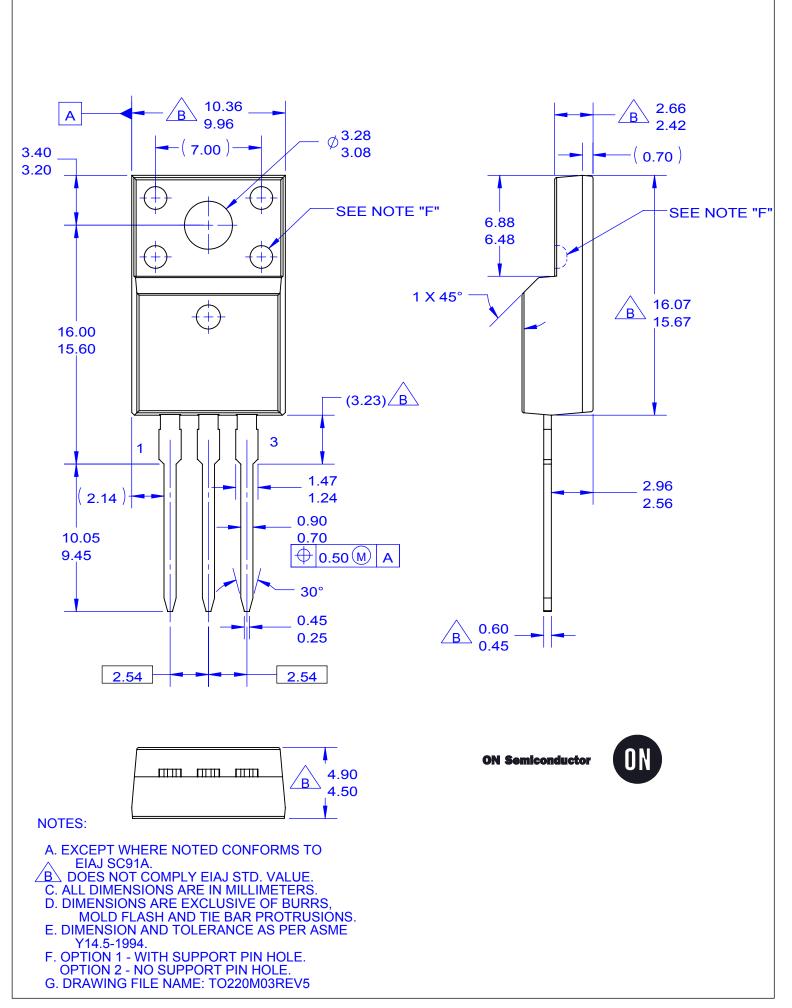


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